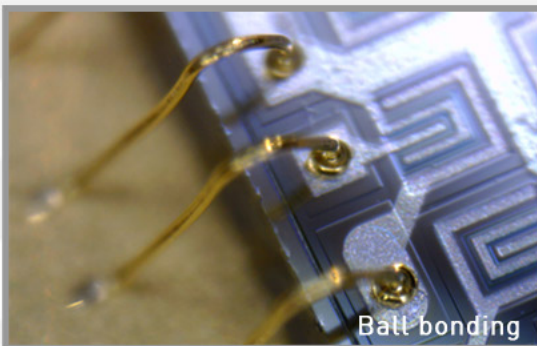


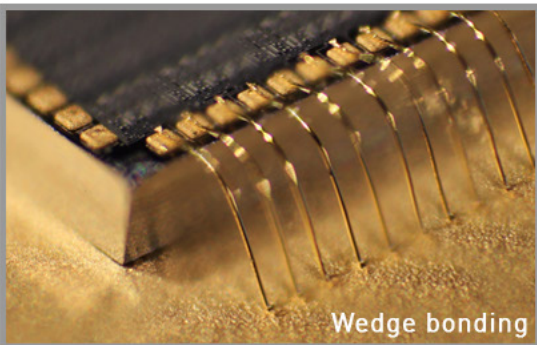


HB05 Wedge & Ball Bonder

Manual Wire Bonder



Ball bonding



Wedge bonding

- + Wedge, Ball, Bump and Ribbon bonding
- + 17 μ to 75 μ Wire and 25 μ x 250 μ Ribbon
- + 4,3" TFT Display & Multi Button
- + Deep-Access Bond Head 16mm
- + Bond Arm Length 165mm
- + Motorized Tail Control
- + 20 Program Storage Capacities
- + Electronic Ball Size Control

HB05 Thermosonic Wire Bonder for Wedge & Ball Bonding

The HB05 is a **Bench Top Size Wire Bonder**, ideal for laboratories and pilot production lines.
One Bond Head for bonding in Ball/Wedge or Wedge/Wedge bonding mode. Only tool change necessary.
Easy operation with **TFT Display**, direct access and simple adjustment of all bond parameters.

Technical Specifications

Bonding Methode Wedge-Wedge, Ball-Wedge, Ribbon- & Bumb- bonding

Gold wire diameter 17 - 75 μ (0,7 - 3 mil)
Aluminium wire diameter 17 - 75 μ (0,7 - 3 mil)
Ribbon size max. 25 x 250 μ (1x 8 mil)

Ultrasonic system 62 kHz Transducer PLL Control
Ultrasonic power 0 - 5 Watt Output
Bond time 0 - 1 sec.
Bond force 5 - 130 cNm
Bonding tool 1,58 \emptyset 19 mm length (0,0624" x 0,750")

Motorised Wire Spool 50,8 mm (2")
Wire termination Bond Head Tear
Wire feed angle 90°
Clamp movement Motorized, Up / Down
Ball size control Electronic

Throat depth 165 mm (6,7")
Fine Table motion 10 mm (0,4 ")
Mouse ratio 6:1

Temperature controller up to 250°C +/- 1°C
Electrical Requirements 100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions 550 x 450 x 250mm
Weight Net 25 kg
Industry Standards CE standards

Accessories:



60mm \emptyset
Heater Stage



90mm \emptyset
Heater Stage



100 x 100mm
Heater Stage



Bondstart Kit



Franz & Fabian Hickmann GbR

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Specifications are subject to change without prior notice